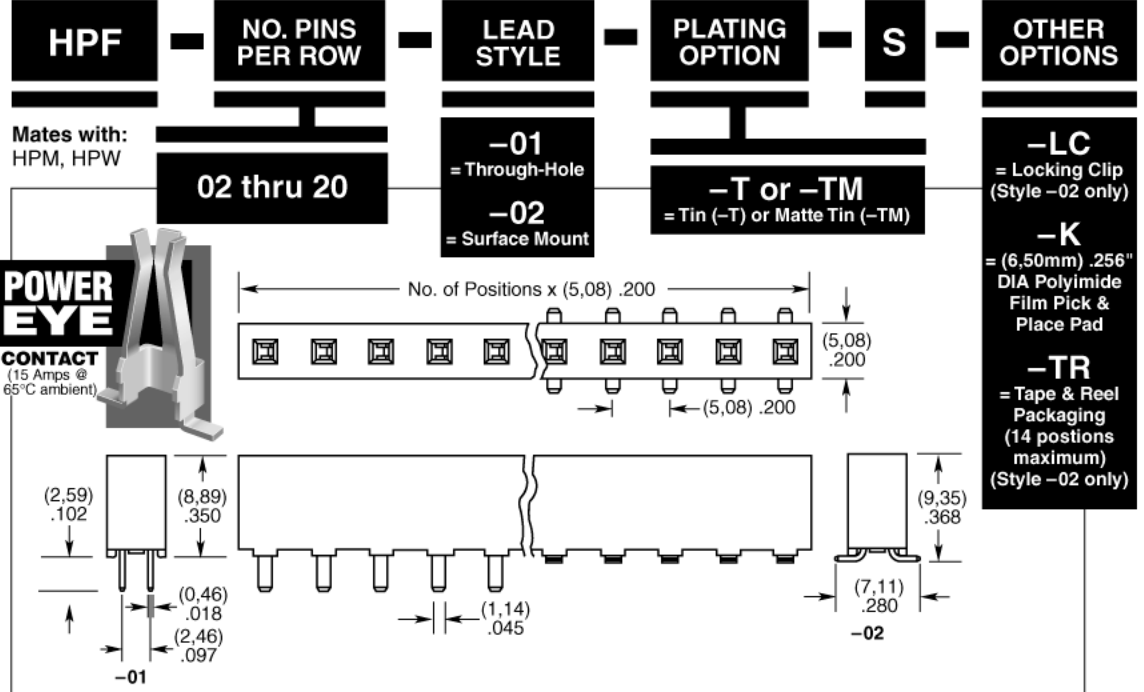


.200" PITCH POWER SOCKETS HPF, PSS SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HPF

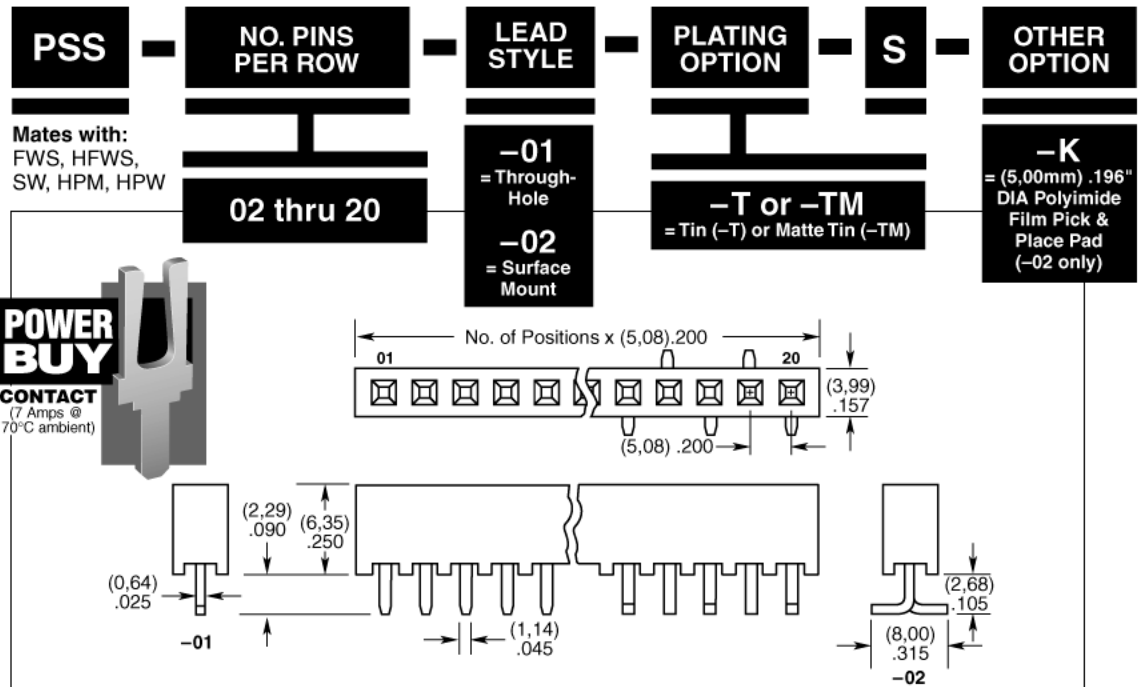
Insulator Material: Black LCP
Contact Material: BeCu
Plating: Sn over 50µ" (1,27µm) Ni
Current Rating: 7.9A @ 30°C Temperature Rise
Insertion Depth: (3,68mm) .145" to (8,26mm) .325" (.368" (9,35mm) plus board thickness minimum for bottom entry)
Insertion Force: (Single contact only) 56oz (15,57N) avg
Withdrawal Force: (Single contact only) 52oz (14,46N) avg
Voltage Rating: 500 VAC mated with HPM
Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x with Matte Sn plating
Lead-Free Solderable: Wave, or SMT with Matte Sn
SMT Lead Coplanarity: (0,15mm) .006" max (02-10) (0,20mm) .008" max (11-20)



SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?PSS

Insulator Material: Black LCP
Contact Material: BeCu
Plating: Sn over 50µ" (1,27µm) Ni
Current Rating: 6.8A @ 30°C Temperature Rise
Insertion Depth: (2,62mm) .103" to (5,03mm) .198"
Insertion Force: (Single contact only) 28oz (7,78N) avg
Withdrawal Force: (Single contact only) 20oz (5,56N) avg
Voltage Rating: 500 VAC mated with FWS
Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x with Matte Sn plating
Lead-Free Solderable: Wave, or SMT with Matte Sn
SMT Lead Coplanarity: (0,15mm) .006" max (02-14) (0,20mm) .008" max (15-20)



Due to technical progress, all designs, specifications and components are subject to change without notice.

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